

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4568270

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST
CONVEYING PARTY DATA	
Name	Execution Date
SYSACOM R&D PLUS INC.	08/14/2017
RECEIVING PARTY DATA	
Name:	BDC CAPITAL INC.
Street Address:	5, PLACE VILLE MARIE
Internal Address:	SUITE 500
City:	MONTREAL
State/Country:	CANADA
Postal Code:	H3B5E7
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	8600692
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	514-845-3533
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Correspondent Name:	MORENCY SOCIÉTÉ D'AVOCATS
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NAME OF SUBMITTER:	CATHERINE OUELLET
SIGNATURE:	/Catherine Ouellet/
DATE SIGNED:	08/28/2017
Total Attachments: 1	
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CONFIRMATION OF SECURITY INTERESTS IN INTELLECTUAL PROPERTY

In consideration of a loan in the amount of six hundred fifty thousand dollars (\$ 650,000.00) granted by **BDC CAPITAL INC.**, whose head office is located at 5 Place Ville Marie, Suite 500, Montreal, Province of Quebec, H3B 5E7, (the "Assignee") in favour of **SYSACOM R&D PLUS INC.**, whose head office is located at 1100, des Canadiens-de-Montréal Avenue, suite 235, C.P.11, Montreal, Province of Quebec, H3B 2S2, (the "Assignor") pursuant to a letter of offer of financing dated July 6, 2017, including its schedules and any amendments, as the case may be, the Assignor hereby confirms having granted to the Assignee, as of this date, hypothecary rights (security interests) in and to the following patent registration:

PATENTS

Title	Application Number	Registration Number
Automatically configurable sensing device	--	8600692 B2

Signed in Montreal, this 14th day of August 2017.

SYSACOM R&D PLUS INC.

By: 
Yves TREMBLAY, President